



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

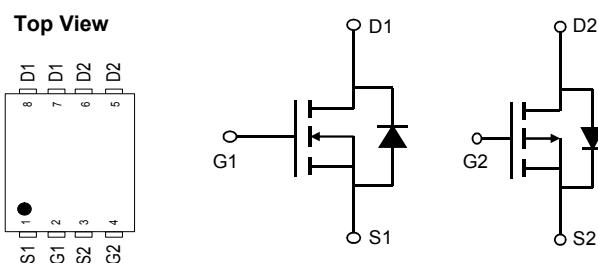
N+P Channel Enhancement Mode Power MOSFET

TF32324

## Features

- N+P Channel
- Enhancement mode
- Very low on-resistance
- Fast Switching
- Pb-free lead plating; RoHS compliant

$V_{DS}$	30	-30	V
$R_{DS(on),TYP}$ $V_{GS}=10\text{ V}$	12	14.5	$\text{m}\Omega$
$R_{DS(on),TYP}$ $V_{GS}=4.5\text{V}$	16	18	$\text{m}\Omega$
$I_D$	30	-28	A



Part ID	Package Type	Marking	Tape and reel information
TF32324	PDFN5x6	32324 : TF32324, TF:tuofeng AA:device code; Y:year code; X:Week	5000pcs/Reel

## Absolute Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating		Unit	
		NMOS	PMOS		
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V	
$V_{DS}$	Drain-Source Breakdown Voltage	30	-30	V	
$T_{STG} T_J$	Storage and operating temperature range	-55 to 175		$^\circ\text{C}$	
$I_D$	Diode Continuous Forward Current	$T_c=25\text{ }^\circ\text{C}$	30	-28	A

## Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested②	$T_c=25\text{ }^\circ\text{C}$	90	-84	A
$I_D$	Continuous Drain Current	$T_c=25\text{ }^\circ\text{C}$	30	-28	A
		$T_c=100\text{ }^\circ\text{C}$	15	-14	
$P_D$	Power dissipation for Dual Operation		$T_c=25\text{ }^\circ\text{C}$	25	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case		6.5		$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		55		$^\circ\text{C/W}$
<b>Drain-Source Avalanche Ratings</b>					
EAS	Avalanche Energy, Single Pulsed		25	32	mJ



## N Channel Electronic Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{DS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	--	--	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_j = 125^\circ\text{C}$ )	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	--	--	100	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.5	2.0	V
$R_{DS(\text{ON})}$	Drain-Source On-State Resistance②	$V_{GS}=10\text{V}, I_D=12\text{A}$	--	12	14	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	--	16	18	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	625	--	pF
$C_{oss}$	Output Capacitance		--	88.3	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	72.5	--	pF
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}, I_D=10\text{A}, V_{GS}=10\text{V}$	--	15	--	nC
$Q_{gs}$	Gate Source Charge		--	3.3	--	nC
$Q_{gd}$	Gate Drain Charge		--	2.1	--	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn on Delay Time	$V_{DD}=15\text{V}, I_D=3.5\text{A}, R_G=3.3\Omega, V_{GS}=10\text{V}$	--	5	--	nS
$t_r$	Turn on Rise Time		--	12	--	nS
$t_{d(off)}$	Turn Off Delay Time		-	21	--	nS
$t_f$	Turn Off Fall Time		--	6	--	nS
<b>Source Drain Diode Characteristics@ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{SD}$	Forward on voltage	$I_{SD}=12\text{A}, V_{GS}=0\text{V}$	--	0.9	1.2	V
$t_{rr}$	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{SD}=12\text{A}, V_{GS}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	11	--	nS
$Q_{rr}$	Reverse Recovery Charge		--	9	--	nC



## P Channel Electronic Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{DS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	--	--	-1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_J = 125^\circ\text{C}$ )	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	--	--	-100	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.2	-1.7	-2.2	V
$R_{DS(\text{ON})}$	Drain-Source On-State Resistance②	$V_{GS}=-10\text{V}, I_D=-15\text{A}$	--	14.5	16	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-10\text{A}$	--	18	20	$\text{m}\Omega$

## Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

$C_{iss}$	Input Capacitance	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1716	--	pF
$C_{oss}$	Output Capacitance		--	227	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	195	--	pF
$Q_g$	Total Gate Charge	$V_{DS}=-15\text{V}, I_D=-5\text{A}, V_{GS}=-10\text{V}$	--	37	--	nC
$Q_{gs}$	Gate Source Charge		--	6.2	--	nC
$Q_{gd}$	Gate Drain Charge		--	5.9	--	nC

## Switching Characteristics

$t_{d(on)}$	Turn on Delay Time	$V_{DD}=-15\text{V}, I_D=-15\text{A}, R_G=3.3\Omega, V_{GS}=-10\text{V}$	--	17	--	ns
$t_r$	Turn on Rise Time		--	45	--	ns
$t_{d(off)}$	Turn Off Delay Time		-	32	--	ns
$t_f$	Turn Off Fall Time		--	37	--	ns

## Source Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

$V_{SD}$	Forward on voltage	$I_{SD}=-15\text{A}, V_{GS}=0\text{V}$	--	-0.92	-1.2	V
$t_{rr}$	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_{SD}=-15\text{A}, V_{GS}=0\text{V}$	--	35	--	nS
			--	23	--	nC

Notes:

①Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$

③Limited by  $TJ_{max}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.5\text{mH}$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 13\text{A}$ ,  $V_{GS} = 10\text{V}$ . Part not recommended for use above this value

④Limited by  $TJ_{max}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.5\text{mH}$ ,  $R_G = 25\Omega$ ,  $I_{AS} = -15\text{A}$ ,  $V_{GS} = -10\text{V}$ . Part not recommended for use above this

## N Channel characteristics curve

Fig.1 Power Dissipation

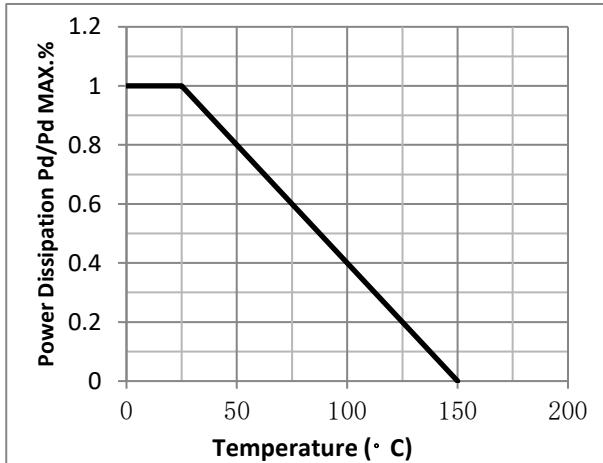


Fig.2 Typical output Characteristics

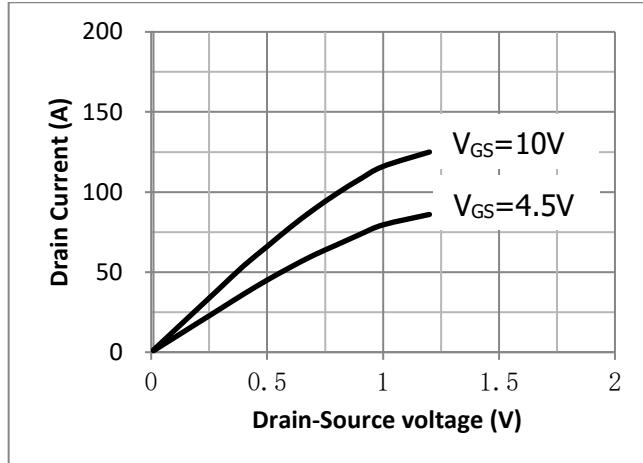


Fig.3 Threshold Voltage V.S Junction Temperature

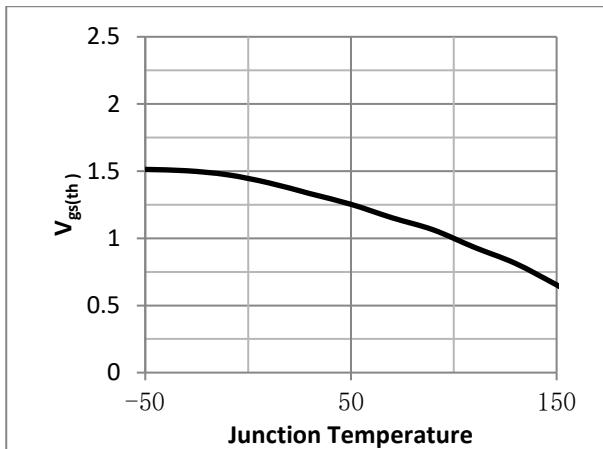


Fig.4 Resistance V.S Drain Current

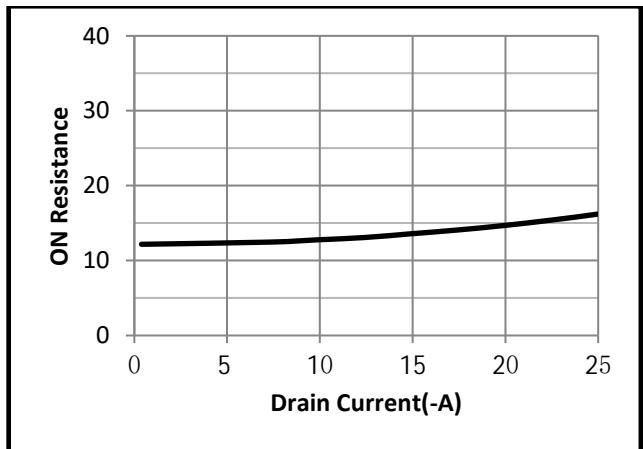


Fig.5 On-Resistance VS Gate Source Voltage

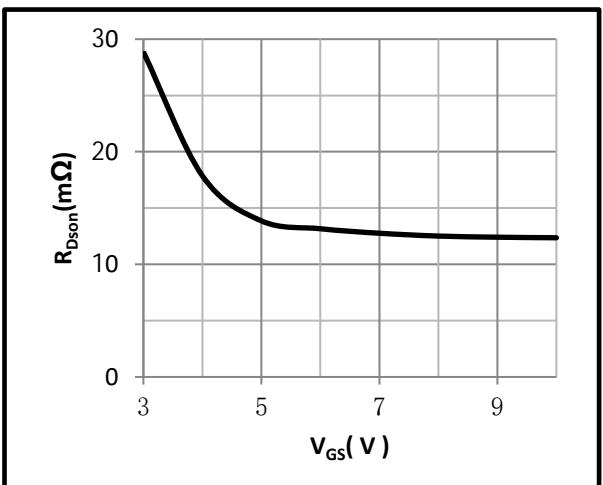
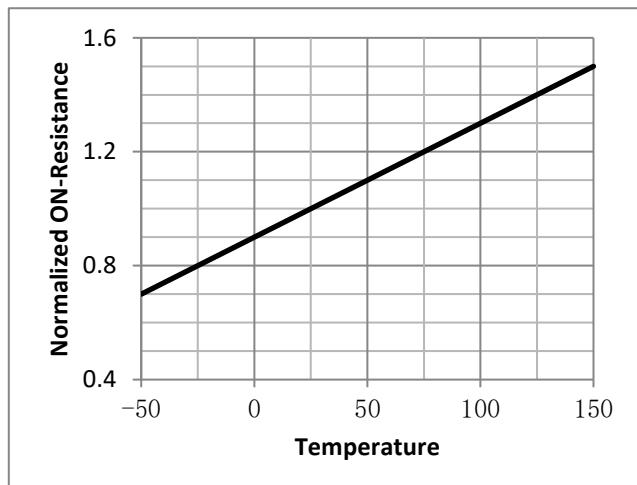


Fig.6 On-Resistance V.S Junction Temperature



## P Channel characteristics curve

Fig.1 Power Dissipation Derating Curve

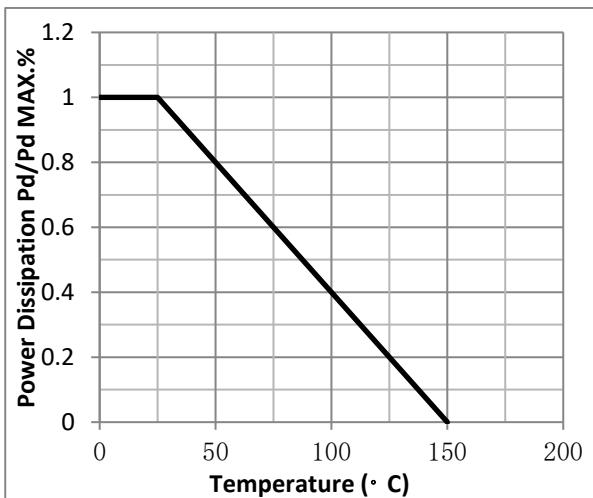


Fig.2 Typical output Characteristics

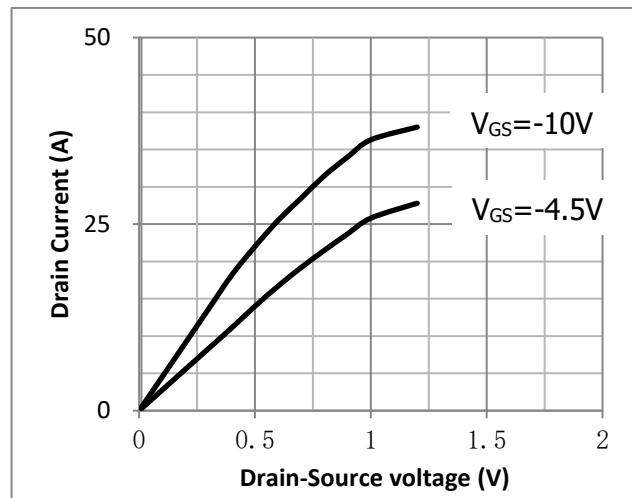


Fig.3 Threshold Voltage V.S Junction Temperature

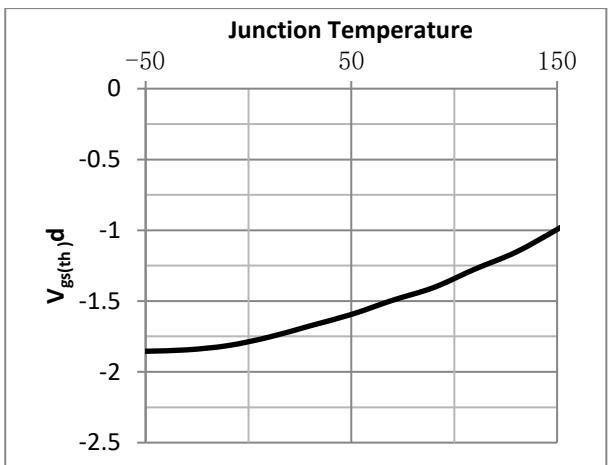


Fig.4 Resistance V.S Drain Current

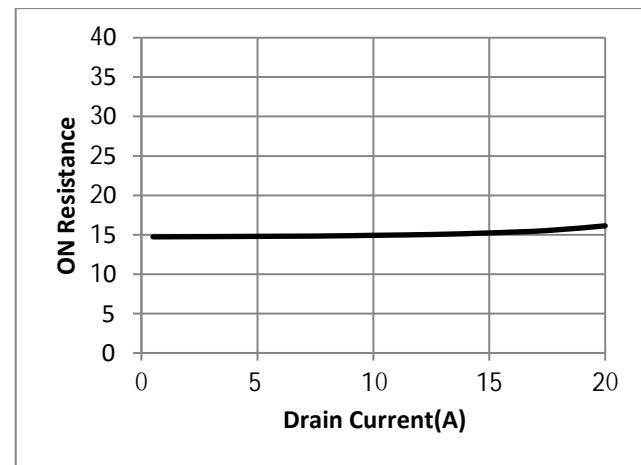


Fig.5 On-Resistance VS Gate Source Voltage

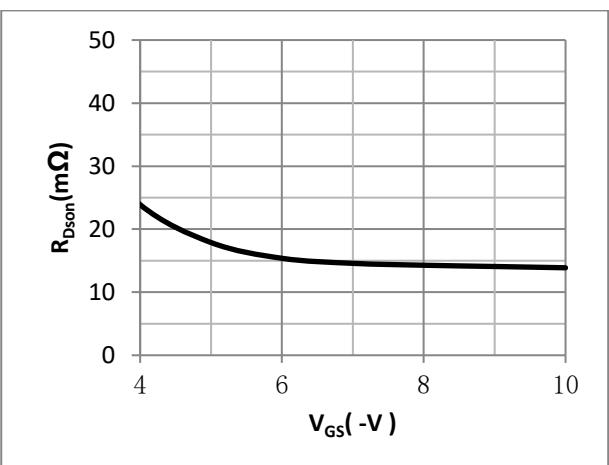
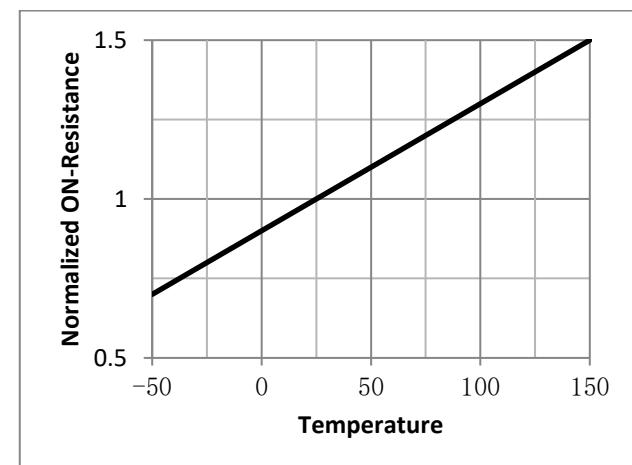


Fig.6 On-Resistance V.S Junction Temperature



## Test Circuit

Fig.1 Switching Time Measurement Circuit

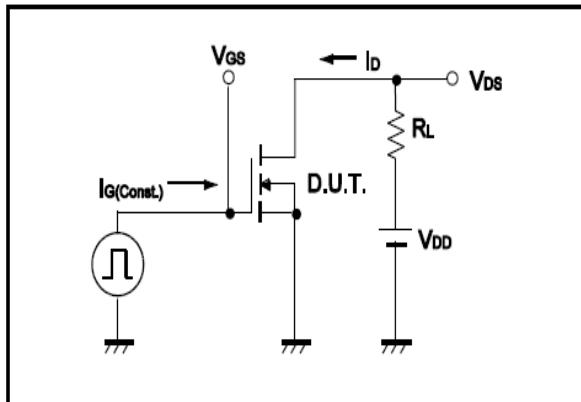


Fig.2 Gate Charge Waveform

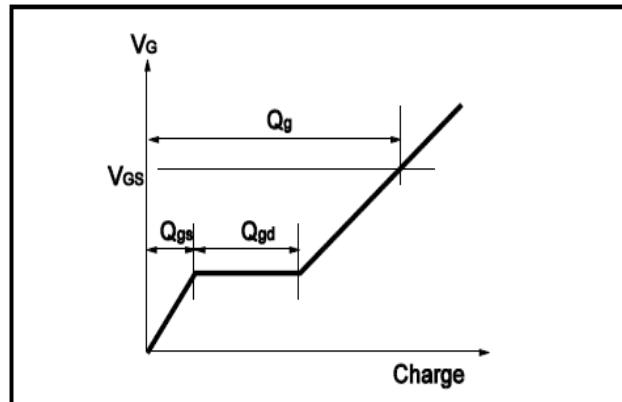


Fig.3 Switching Time Measurement Circuit

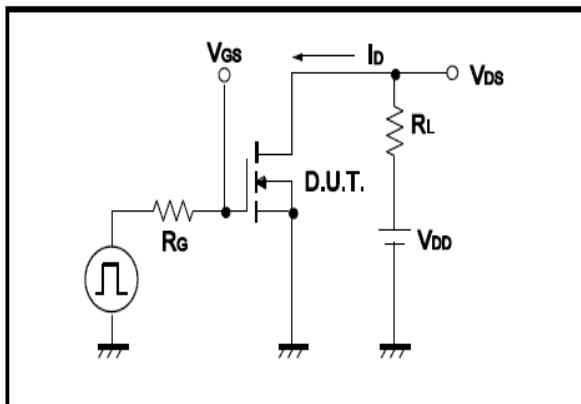


Fig.4 Gate Charge Waveform

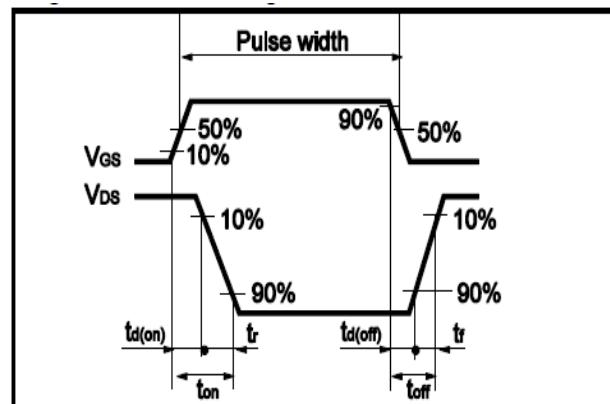


Fig.5 Avalanche Measurement Circuit

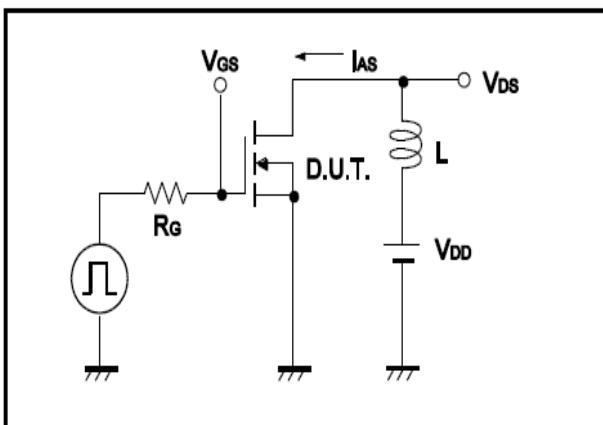
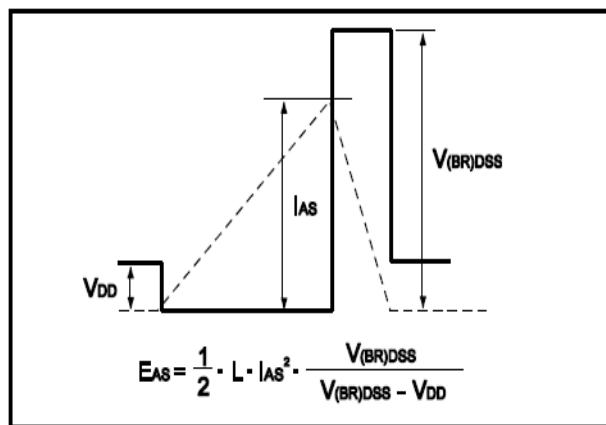
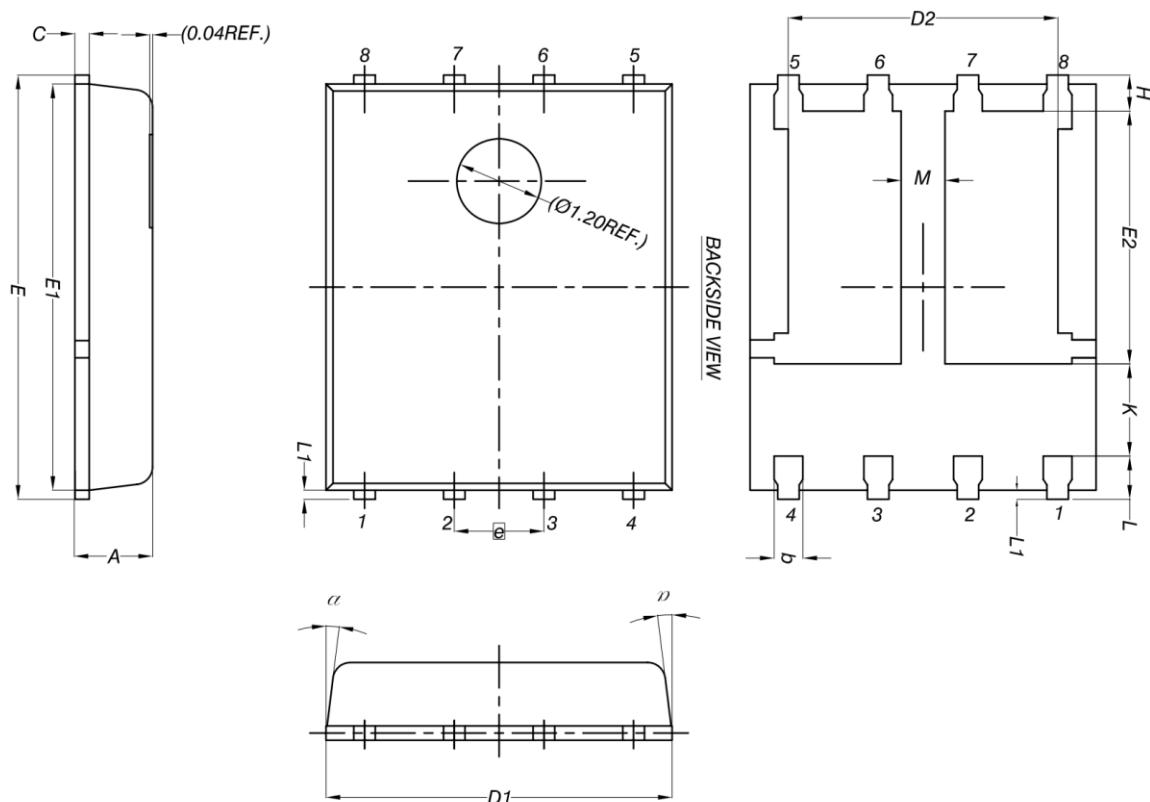


Fig.6 Avalanche Waveform



## PDFN5\*6 Package Outline Data

Unit: mm



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	-	-
$\alpha$	0°	-	12°

